TTTC IN GENERAL

PURPOSE: The Test Technology Technical Council is a volunteer professional organization sponsored by the IEEE Computer Society. The goals of TTTC are to contribute to members' professional development and advancement and to help them solve engineering problems in electronic test, and help advance the state-of-the-art. In particular, TTTC aims at facilitating the knowledge flow in an integrated manner, to ensure overall quality in terms of technical excellence, fairness, openness, and equal opportunities.

MEMBERSHIP: Membership is open to all individuals interested in test engineering at a professional level.

DUES: There are NO dues for TTTC membership and no parent-organization membership requirements.

BENEFITS: The TTTC members benefit from personal association with other test professionals. They may have the opportunity to be involved on a wide range of committees. They receive appropriate and updated information and announcements. There are substantial reductions in fees for TTTC-sponsored meetings and tutorials for members of IEEE and/or IEEE Computer Society.

TTTC ACTIVITIES

TECHNICAL MEETINGS: To spread technical knowledge and advance the state-of-the-art, TTTC sponsors many well-known conferences and symposia and holds numerous regional and topical workshops worldwide.

STANDARDS: TTTC initiates, nurtures and encourages new test standards. TTTC-initiated Working Groups have produced numerous IEEE standards, including the 1149 series used throughout the industry.

TECHNICAL ACTIVITIES: TTTC sponsors a number of Technical Activity Committees (TACs) that address emerging test technology topics and guide a wide range of activities.

TUTORIALS and EDUCATION: TTTC sponsors a comprehensive Test Technology Educational Program (TTEP). This program provides opportunities for design and test professionals to update and expand their knowledge base in test technology, and to earn official accreditation from IEEE TTTC, upon the completion of four full day tutorials proposed by TTEP.

TTTC CONTACT

TTTC On-Line: The TTTC Web Site at http://tab.computer.org/tttc offers samples of the TTTC Newsletter, information about technical activities, conferences, workshops and standards, and links to the Web pages of a number of TTTC-sponsored technical meetings.

Becoming a MEMBER: Becoming a TTTC member is extremely simple. You may either contact by phone or e-mail the TTTC office, or fill out and submit a TTTC application form, or visit the membership section of the TTTC web site.

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TTTC-Sponsored Technical Meetings in 2010

For the most current information, please visit the TTTC website (http://tab.computer.org/tttc) or TTTC Events website (http://www.tttc-events.org)

1/23-1/25 Int’l Sym on Electronic, Design, Test and Applications (DELTA), Ho Chi Minh City, Vietnam

3/8-3/12 Design, Automation and Test in Europe (DATE), Dresden, Germany

3/23-3/24 Workshop on Silicon Errors in Logic - System Effects (SESEL), Stanford, CA, USA

3/28-3/31 Latin American Test Workshop (LATW), Punta del Este, Uruguay

4/15-4/17 Design & Diagnosis of Electronic Circuits & Systems Workshop (DDECS), Vienna, Austria

4/19-4/22 VLSI Test Symposium (VTS), Santa Cruz, CA, USA

4/22-4/23 Workshop on Test of Wireless Circuits and Systems (WTW), Santa Cruz, CA, USA

5/9-5/12 Workshop on Signal Propagation on Interconnects (SPI), Hildesheim, Germany

5/24-5/28 European Test Symposium (ETS), Praha, Czech Republic

5/28-5/30 Int’l Conference on Automation, Quality & Testing, Robotics (AQTR), Cluj-Napoca, Romania

6/7-6/9 Int’l Mixed-Signals, Sensors, and Systems Test Workshop (IM3STW), La Grande Motte, France

6/10-6/12 Int’l High Level Design Validation and Test Workshop (HLDV), Anaheim, CA, USA

6/13-6/14 Int’l Symposium on Hardware-Oriented Security and Trust (HOST), Anaheim, CA, USA

6/14 Int’l Workshop on Design for Manufacturability & Yield (DfM&Y), Anaheim, CA, USA

7/5-7/7 International On-Line Testing Symposium (IOLTS), Corfu Island, Greece

9/14-9/16 Board Test Workshop (BTW), Fort Collins, CO, USA

11/4-11/5 Int’l Workshop on Testing Embedded and Core-Based System-Chips (TECS), Austin, TX, USA

12/1-12/4 Asian Test Symposium (ATS), Shanghai, China

12/5-12/6 Workshop on RTL and High Level Testing (WRHLT), Shanghai, China

12/6-12/8 International Workshop on Microprocessor Test and Verification (MTV), Austin, TX, USA

TBD International Workshop on Design & Test (IDT), TBD

TBD Int’l Workshop on Memory Technology, Design and Testing (MTDT), TBD

TBD Int’l Workshop on Testing Embedded and Core-Based System-Chips (TECS), Online

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